

4

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D

D

C

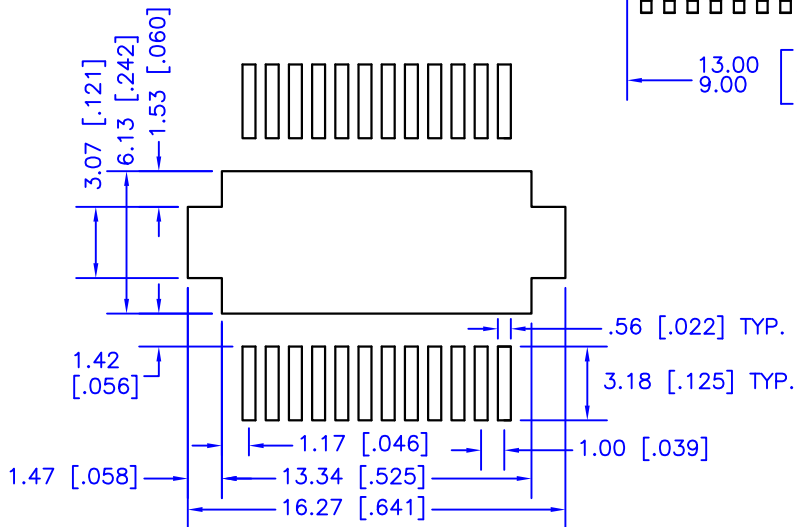
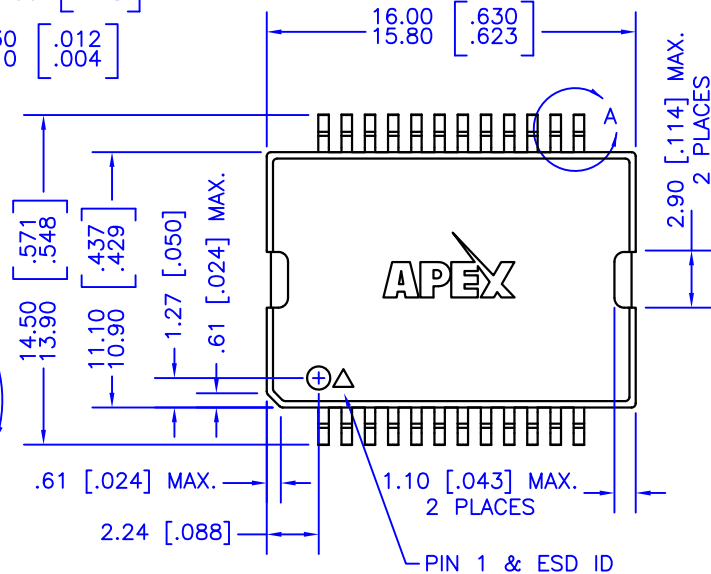
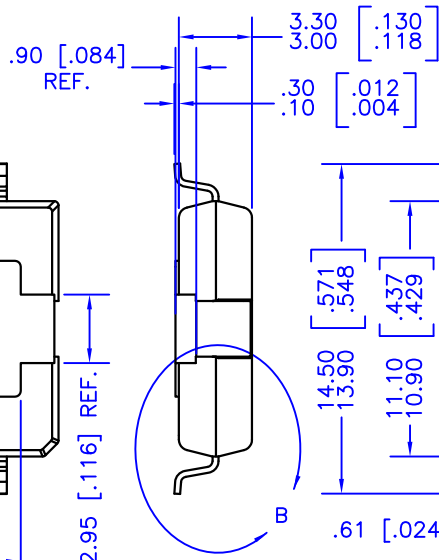
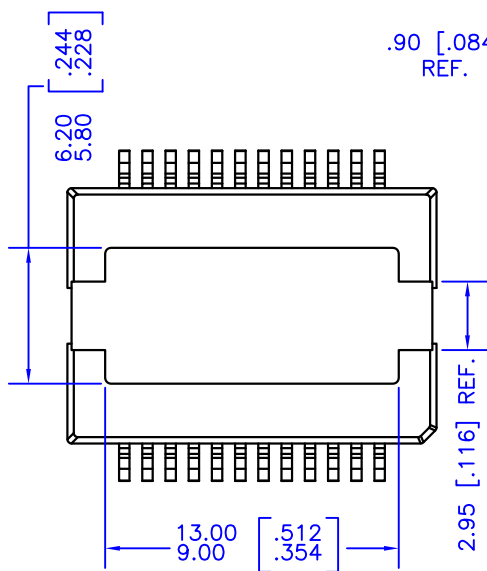
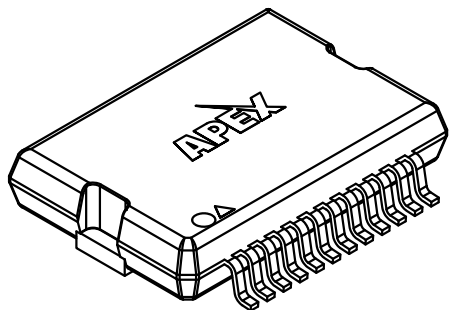
C

B

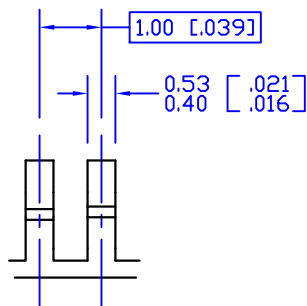
B

A

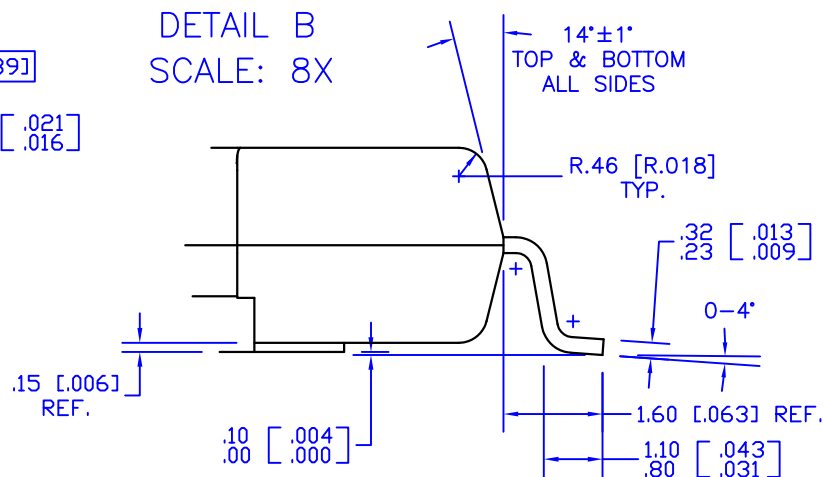
A



Surface Mount Layout



DETAIL A
SCALE: 8X



DETAIL B
SCALE: 8X

NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Pins & Heat Slug: CDA 194 copper with bismuth solder finish
5. Mold compound: MP-8000AN epoxy
6. Package weight: .086 oz. [2.44 g]
7. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED
.XX = ±.01 [0.254]
.XXX = ±.005 [0.127]
ANG. = ±5°



TITLE: JEDEC MO-166, 24-pin PSOP		MODEL:
SUBJECT: PACKAGE OUTLINE		DF
ENGINEER: D-M	DRAWN BY: R.MORG	DATE: 29MAY13
DWG. NO: 13227	REV: E	
SH. OF: 1 1		

FILENAME: DF	REV: E	DATE: 29MAY13
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